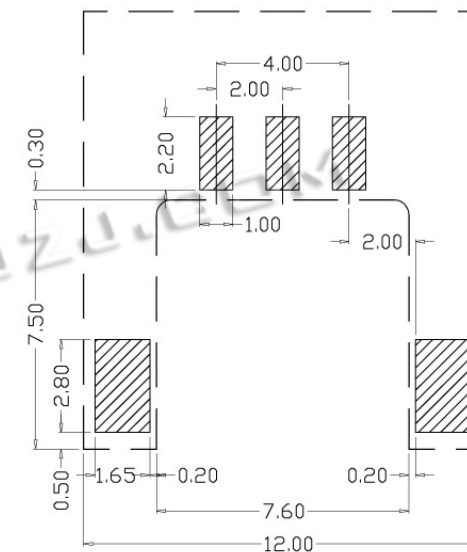
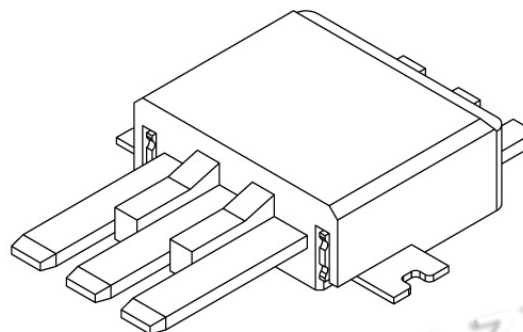
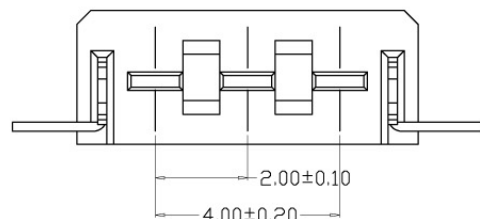
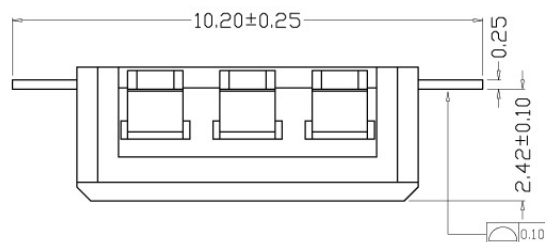
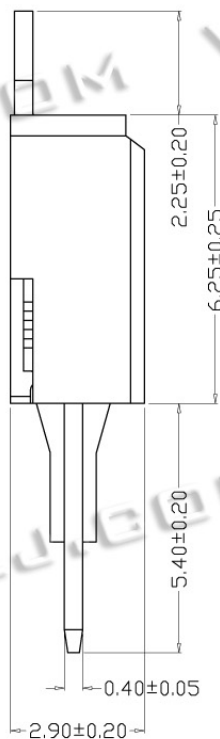
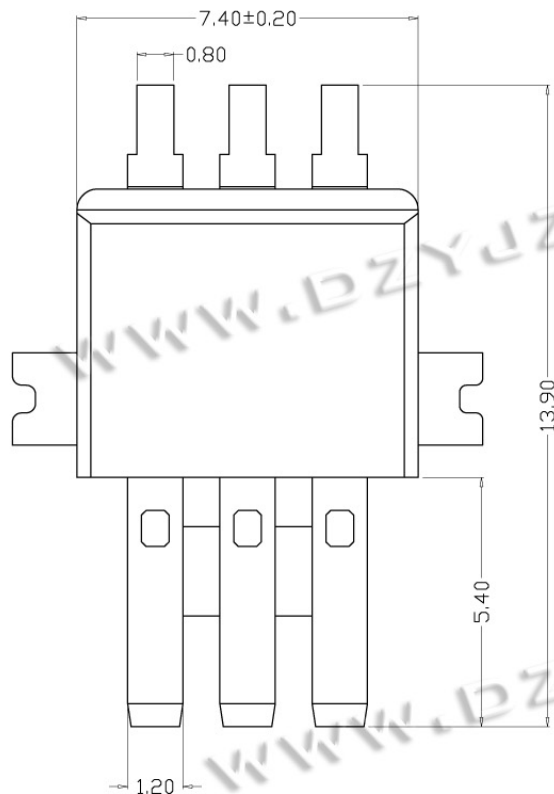




PCB LAYOUT



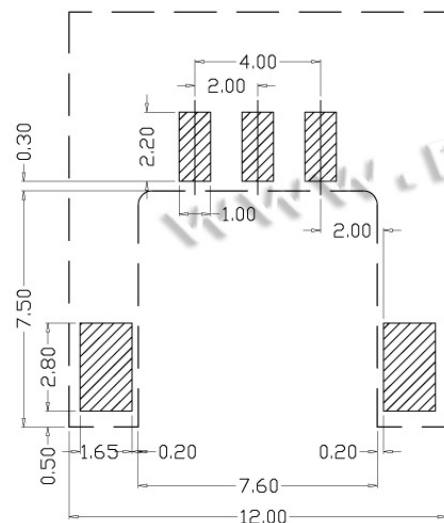
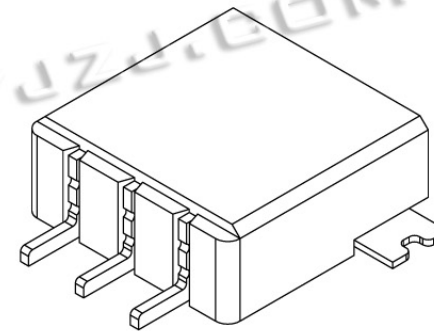
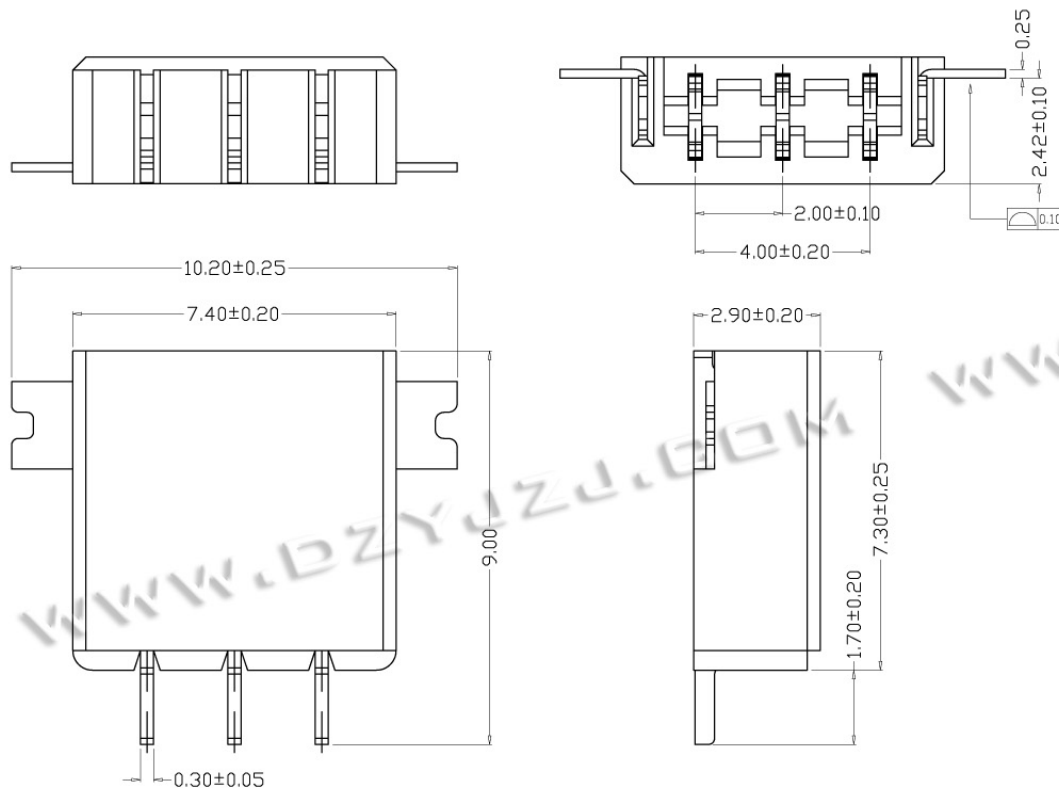
SPECIFICATIONS

- 1、Current Rating: 1A AC, DC
- 2、Voltage Rating: 250V AC, DC
- 3、Temperature Range: -25℃~+85℃
- 4、Contact Resistance: 30mΩ Max
- 5、Insulation Resistance: 1000MΩ Min
- 6、Withstanding Voltage: 1500V AC/minute
- 7、Material: Wafer LCP, UL94V-0
PIN Brass Tin-plated
Solder pad Brass Tin-plated



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2° X.X' ±0.5°	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 20015 3P贴片WAFER
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC171-WF03-200
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.
			DRAW NO: HYC-1909291207
			SHEET NO. 1 OF 1



PCB LAYOUT

SPECIFICATIONS

- 1、Current Rating: 1A AC, DC
- 2、Voltage Rating: 250V AC, DC
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- 5、Insulation Resistance: 1000MΩ Min
- 6、Withstanding Voltang: 1500V AC/minute
- 7、Material: Wafer LCP, UL94V-0
PIN Brass Tin-plated
Solder tad Brass Tin-plated



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2° X.X' ±0.5'	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 20016 3P卧贴WAFER	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	HYC169-WF03-200
 UNIT: mm [inch]	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.	
			DRAW NO:	HYC-1909291159
SCALE:1:1 SIZE: A4			SHEET NO.	1 OF 1